TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (U-MOSIII)

# TPCS8212

# Lithium Ion Battery Applications

Has a small footprint.

• Low drain-source ON resistance: RDS (ON) = 16 m $\Omega$  (typ.)

- High forward transfer admittance:  $|Y_{fs}| = 11 \text{ S (typ.)}$
- Low leakage current:  $IDSS = 10 \mu A (max) (VDS = 20 V)$
- Enhancement-mode:  $V_{th} = 0.5 \sim 1.2 \text{ V (VDS} = 10 \text{ V, ID} = 200 \mu\text{A})$
- Common drain

## **Maximum Ratings (Ta = 25°C)**

Char	acteristics	Symbol	Rating	Unit	
Drain-source voltage		$V_{DSS}$	20	V	
Drain-gate voltag	ge (R <sub>GS</sub> = 20 kΩ)	$V_{DGR}$	20	V	
Gate-source volt	age	V <sub>GSS</sub>	±12	V	
Drain current	DC (Note 1)	I <sub>D</sub>	6	А	
Diain current	Pulse (Note 1)	$I_{DP}$	24	A	
Drain power	Single-device operation (Note 3a)	P <sub>D (1)</sub>	1.1		
dissipation (t = 10 s) (Note 2a)	Single-device value at dual operation (Note 3b)	P <sub>D (2)</sub>	0.75	W	
Drain power dissipation (t = 10 s) (Note 2b)	Single-device operation (Note 3a)	P <sub>D (1)</sub>	0.6	VV	
	Single-device value at dual operation (Note 3b)	P <sub>D (2)</sub>	0.35		
Single pulse avalanche energy (Note 4)		E <sub>AS</sub>	46.8	mJ	
Avalanche curre	Avalanche current		6	Α	
Repetitive avalanche energy Single-device value at dual operation (Note 2a, 3b, 5)		E <sub>AR</sub>	0.075	mJ	
Channel temperature		T <sub>ch</sub>	150	°C	
Storage temperature range		T <sub>stg</sub>	-55~150	°C	

Unit: mm

(0.525)

1. DRAIN
2. 3. SOURCE
4. GATE
8. DRAIN

JEDEC

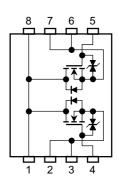
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Weight: 0.035 g (typ.)

# **Circuit Configuration**



Note: (Note 1), (Note 2), (Note 3), (Note 4), (Note 5) Please see next page.

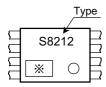
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This transistor is an electrostatic sensitive device. Please handle with caution.

### **Thermal Characteristics**

Characteristics	Symbol	Max	Unit		
The arm of an elistence of the arm of the contribute	Single-device operation (Note 3a)	R <sub>th (ch-a) (1)</sub>	114	°C/W	
Thermal resistance, channel to ambient (t = 10 s) (Note 2a)	Single-device value at dual operation (Note 3b)	R <sub>th</sub> (ch-a) (2)	167		
Thermal resistance, channel to ambient	Single-device operation (Note 3a)	R <sub>th (ch-a) (1)</sub>	208		
(t = 10 s) (Note 2b)	Single-device value at dual operation (Note 3b)	R <sub>th (ch-a) (2)</sub>	357	°C/W	

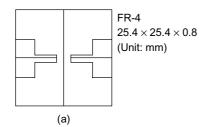
### Marking (Note 6)



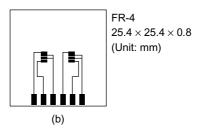
Note 1: The channel temperature should not exceed 150°C.

#### Note 2:

a) Device mounted on a glass-epoxy board (a)



b) Device mounted on a glass-epoxy board (b)



### Note 3:

- a) The power dissipation and thermal resistance values are shown for a single device (During single-device operation, power is only applied to one device.).
- b) The power dissipation and thermal resistance values are shown for a single device (During dual operation, power is evenly applied to both devices.).
- Note 4:  $V_{DD} = 16 \text{ V}$ ,  $T_{ch} = 25^{\circ}\text{C}$  (initial), L = 1.0 mH,  $R_G = 25 \Omega$ ,  $I_{AR} = 6 \text{ A}$
- Note 5: Repetitive rating; pulse width limited by max channel temperature.
- Note 6: o on lower right of the marking indicates Pin 1.

  \* shows lot number. (Year of manufacture: last decimal digit of the year of manufacture, Month of manufacture: January to December are denoted by letters A to L respectively)

2



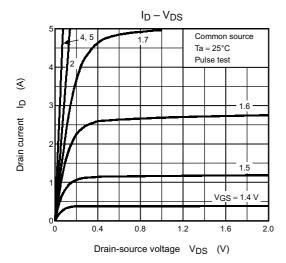
# Electrical Characteristics (Ta = 25°C)

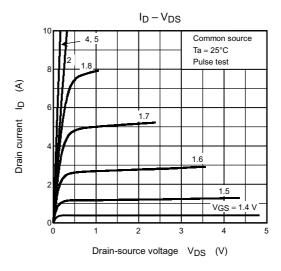
Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cui	rrent	I <sub>GSS</sub>	$V_{GS} = \pm 10 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±10	μΑ
Drain cut-OFF cเ	urrent	I <sub>DSS</sub>	V <sub>DS</sub> = 20 V, V <sub>GS</sub> = 0 V	_	_	10	μΑ
Drain-source bre	akdown voltago	V (BR) DSS	$I_D = 10 \text{ mA}, V_{GS} = 0 \text{ V}$	20	_	_	V
Diam-source bre	akuowii voitage	V (BR) DSX	$I_D = 10 \text{ mA}, V_{GS} = -12 \text{ V}$	8	_	_	V
Gate threshold v	oltage	V <sub>th</sub>	$V_{DS} = 10 \text{ V}, I_D = 200 \mu\text{A}$	0.5	_	1.2	V
			$V_{GS} = 2.0 \text{ V}, I_D = 4.2 \text{ A}$	_	26	45	mΩ
Drain-source ON	resistance	R <sub>DS (ON)</sub>	$V_{GS} = 2.5 \text{ V}, I_D = 4.2 \text{ A}$	_	21	29	
			V <sub>GS</sub> = 4.0 V, I <sub>D</sub> = 4.8 A	_	16	24	
Forward transfer	admittance	Y <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 3.0 A	5.5	11	_	S
Input capacitance		C <sub>iss</sub>		_	1590	_	
Reverse transfer	capacitance	C <sub>rss</sub>	$V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	_	180	_	pF
Reverse transfer capacitance Output capacitance		C <sub>oss</sub>		_	200	_	
	Rise time	t <sub>r</sub>	VGS 5 V	_	6.4	_	
Switching time	Turn-ON time	t <sub>on</sub>		_	22	_	ne
	Fall time	t <sub>f</sub>		_	10	_	ns
	Turn-OFF time	t <sub>off</sub>	V <sub>DD</sub> ≃ 10 V Duty ≦ 1%, t <sub>W</sub> = 10 μs		42	_	
Total gate charge (gate-source plus gate-drain)		Qg			20	_	
Gate-source charge 1		Q <sub>gs1</sub>	$V_{DD} \simeq 16 \text{ V}, V_{GS} = 5 \text{ V}, I_{D} = 6 \text{ A}$		3.5		nC
Gate-drain ("miller") charge		Q <sub>gd</sub>			4.5		

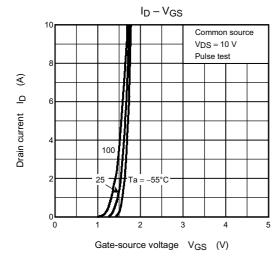
# **Source-Drain Diode Ratings and Characteristics (Ta = 25°C)**

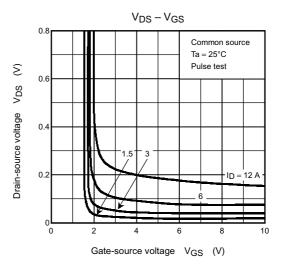
Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Drain reverse current	Pulse (Note 1)	I <sub>DRP</sub>	_	_	_	24	Α
Diode forward voltage		$V_{DSF}$	$I_{DR} = 6 A, V_{GS} = 0 V$			-1.2	V

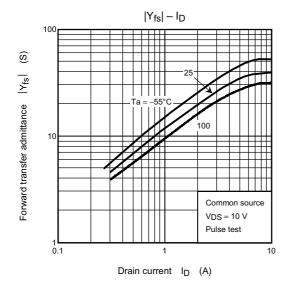
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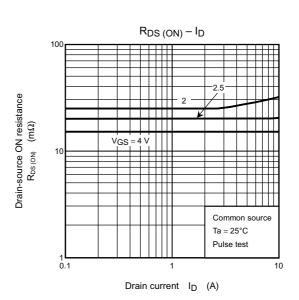




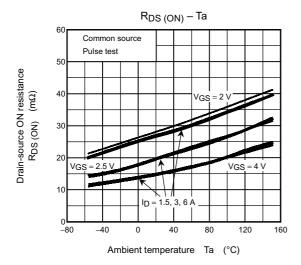


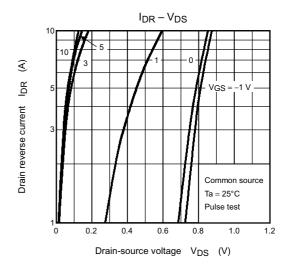


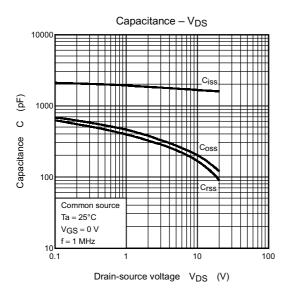


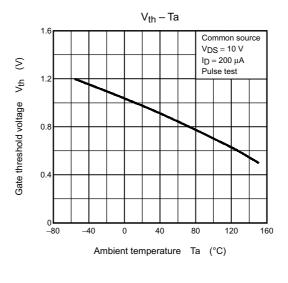


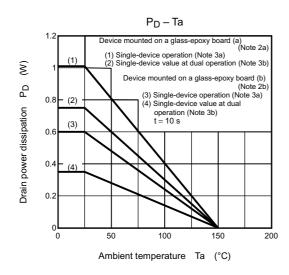
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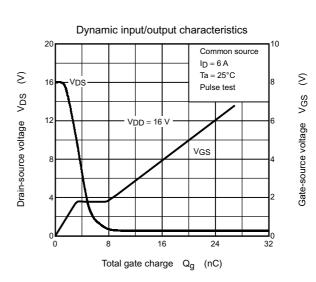


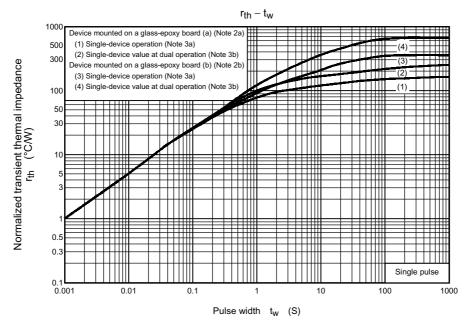




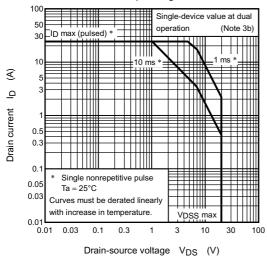












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